

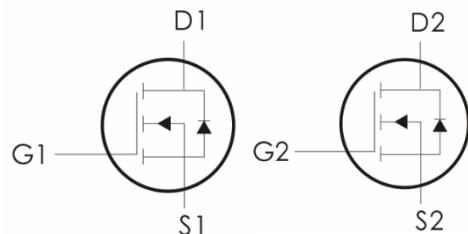
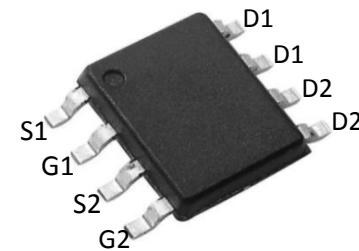
## Description:

This Dual N-Channel MOSFET uses advanced trench technology and design to provide excellent  $R_{DS(on)}$  with low gate charge.

It can be used in a wide variety of applications.

## Features:

- 1)  $V_{DS}=20V, I_D=12A, R_{DS(ON)}<11m\Omega @V_{GS}=4.5V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra  $R_{DS(ON)}$ .
- 5) Excellent package for good heat dissipation.



## Absolute Maximum Ratings: ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 10$	V
$I_D$	Continuous Drain Current-	12	A
	Pulsed Drain Current <sup>1</sup>	45	
$P_D$	Power Dissipation	2	W
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	°C

## Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{Theta}$	Thermal Resistance,Junction to Ambient <sup>2</sup>	62.5	°C/W

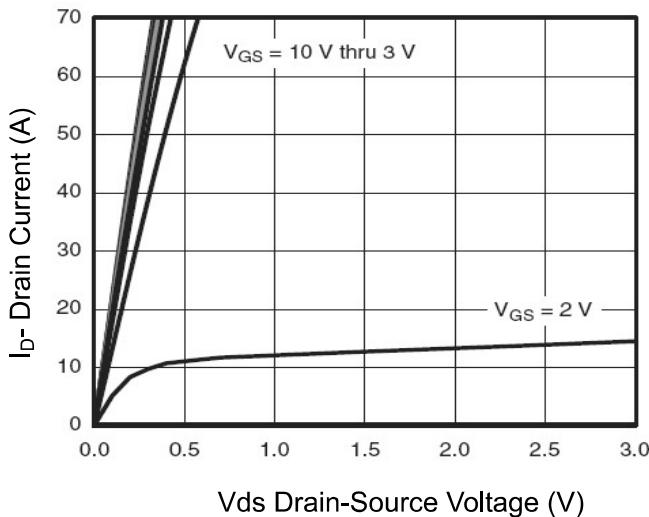
**Electrical Characteristics:** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_D=250 \mu\text{A}$	20	---	---	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=20\text{V}$	---	---	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 10\text{V}, V_{\text{DS}}=0\text{A}$	---	---	$\pm 100$	nA
<b>On Characteristics<sup>3</sup></b>						
$V_{\text{GS}(\text{th})}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_D=250 \mu\text{A}$	0.5	0.7	1	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On Resistance	$V_{\text{GS}}=4.5\text{V}, I_D=5\text{A}$	---	8	11	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}, I_D=4\text{A}$	---	10	13	
$G_{\text{FS}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}, I_D=8\text{A}$	---	15	---	S
<b>Dynamic Characteristics<sup>4</sup></b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	1800	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	230	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	200	---	
<b>Switching Characteristics<sup>4</sup></b>						
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DS}}=10\text{V}, R_L=1.2 \Omega$ $R_{\text{GEN}}=3 \Omega, V_{\text{GS}}=10\text{V},$	---	2.5	---	ns
$t_r$	Rise Time		---	7.2	---	ns
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	49	---	ns
$t_f$	Fall Time		---	10.8	---	ns
$Q_g$	Total Gate Charge		---	17.9	---	nC
$Q_{\text{gs}}$	Gate-Source Charge	$V_{\text{GS}}=4.5\text{V}, V_{\text{DS}}=10\text{V},$ $I_D=8\text{A}$	---	1.5	---	nC
$Q_{\text{gd}}$	Gate-Drain "Miller" Charge		---	4.7	---	nC
<b>Drain-Source Diode Characteristics</b>						
$V_{\text{SD}}$	Source-Drain Diode Forward Voltage <sup>3</sup>	$V_{\text{GS}}=0\text{V}, I_S=4.5\text{A}$	---	---	1.2	V
$I_s$	Maximum Body-Diode Continuous Current <sup>2</sup>		---	---	12	

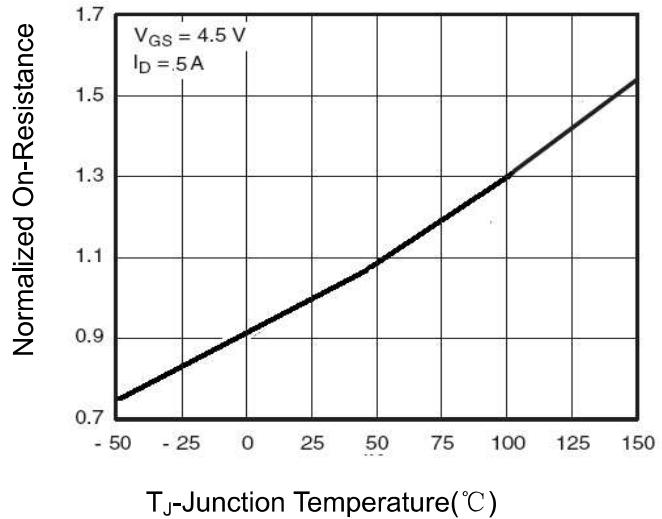
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

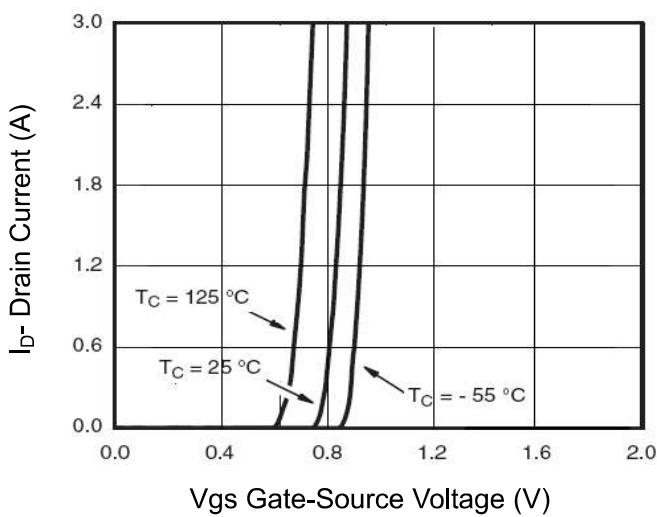
**Typical Characteristics:** ( $T_c=25^\circ\text{C}$  unless otherwise noted)



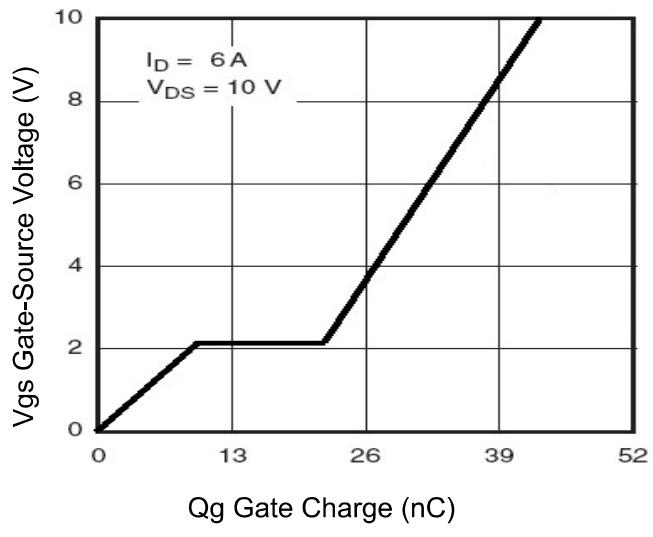
**Figure 1 Output Characteristics**



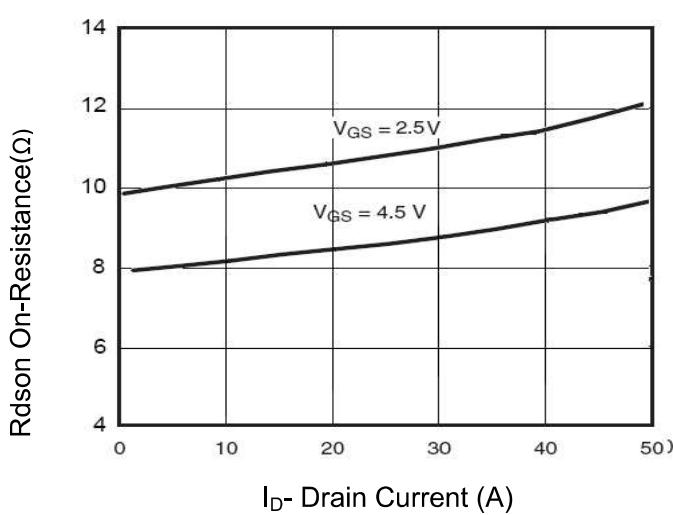
**Figure 2 Rdson-Junction Temperature**



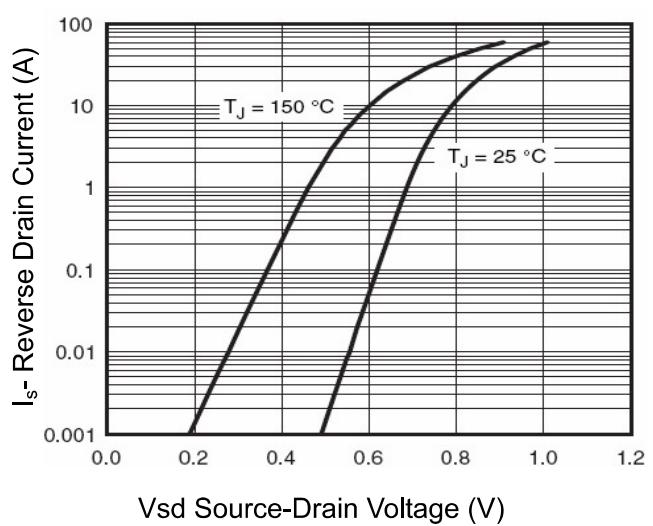
**Figure 3 Transfer Characteristics**



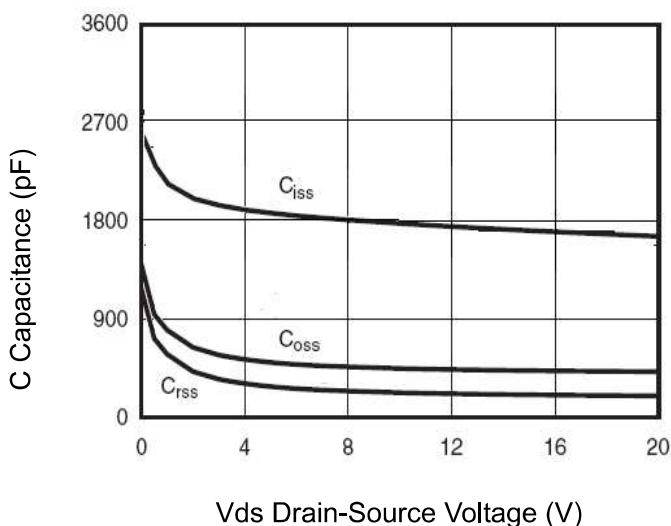
**Figure 4 Gate Charge**



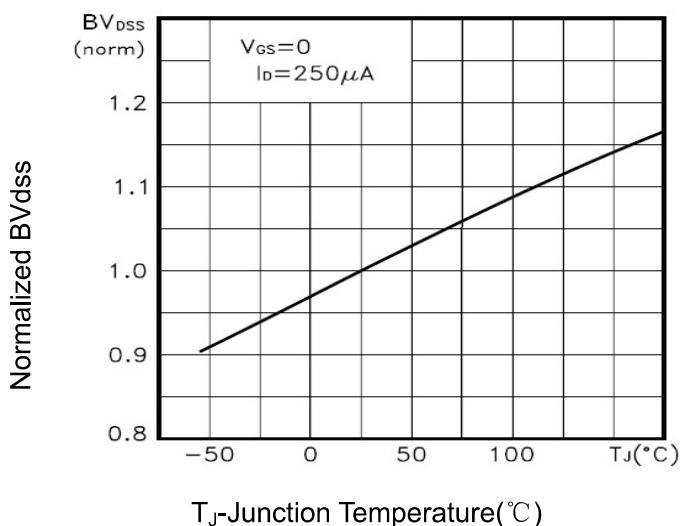
**Figure 5 Rdson- Drain Current**



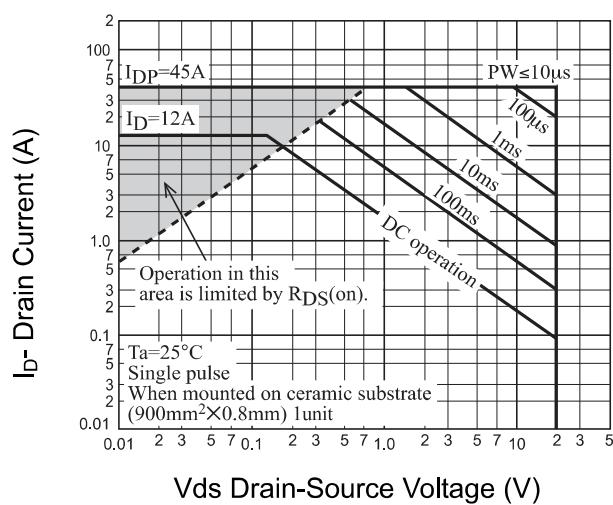
**Figure 6 Source- Drain Diode Forward**



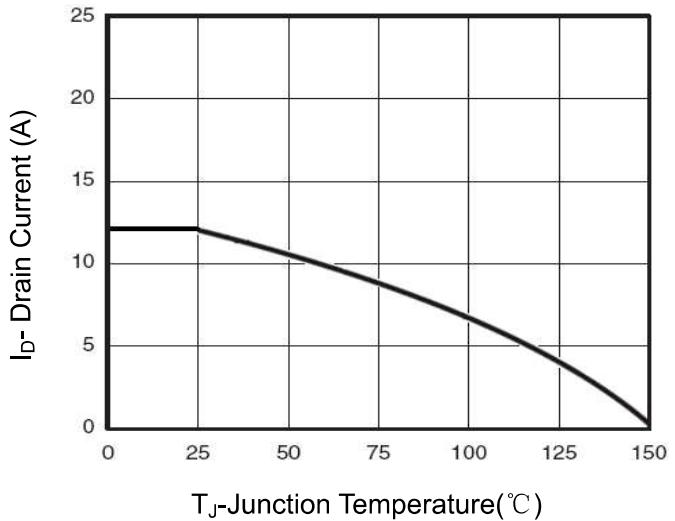
**Figure 7 Capacitance vs Vds**



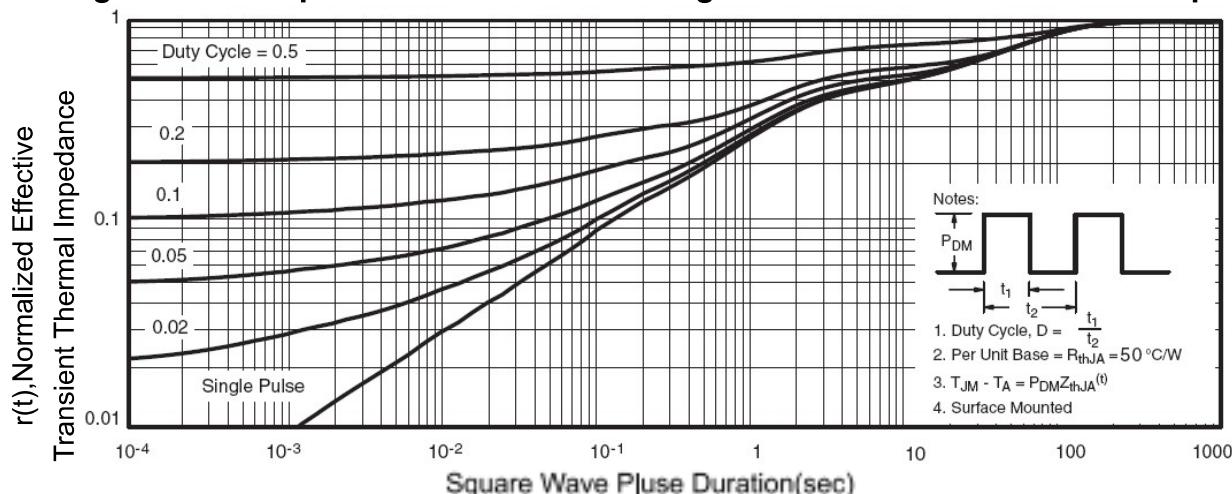
**Figure 8  $BV_{dss}$  vs Junction Temperature**



**Figure 9 Safe Operation Area**



**Figure 10 Current vs Junction Temperature**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

